

In the Claims:

1-11. (Canceled)

12. (New) Process for producing thermal insulation adhesives and reinforcing mortars comprising:

polymerizing one or more monomers having one or more carbonyl groups, wherein at least one of the one or more carbonyl groups are chosen from aldehyde and keto groups, forming one or more copolymers having one or more carbonyl groups,

stabilizing the one or more copolymers with at least one protective colloid,

drying the stabilized copolymers forming a dispersion powder,

homogenously mixing the dispersion powder with one or more formulation constituents thereby forming a dry mix, and

mixing the dry mix with water thereby producing the thermal insulation adhesives and reinforcing mortars.

13. (New) Process according to claim 12 wherein the one or more monomers having carbonyl groups are chosen from acrolein, vinyl acetoacetate, allyl acetoacetate, diacetoneacrylamide, vinyl methyl ketone, acetoacetylated hydroxyalkyl acrylates and acetoacetylated hydroxyalkyl methacrylates.

14. (New) Process according to claim 12 wherein the one or more copolymers having one or more carbonyl groups are present in an amount of from 0.1 to 15% by weight, based on total weight of the copolymer.

15. (New) Process according to claim 12 wherein the one or more copolymers having one or more carbonyl groups further comprise at least one monomer chosen from vinyl esters, vinyl aromatics, acrylic esters, methacrylic esters, fumaric esters and maleic esters.

16. (New) Process according to claim 12 wherein the one or more copolymers having one or more carbonyl groups further comprise at least one monomer chosen from methacrylic and acrylic esters modified with epoxide groups or hydroxyl groups and the anhydrides of acrylic and methacrylic acids, amides of acrylic and methacrylic acids and their isobutoxy ethers and n-butoxy ethers, ethylenically unsaturated monocarboxylic and dicarboxylic acids and their anhydrides and amides, ethylenically unsaturated sulfonic acids and their salts, vinyl sulfonic acids, vinyl chlorides, monounsaturated or polyunsaturated olefins and acryloxypropyltri(alkoxy)silanes, methacryloxypropyltri(alkoxy)silanes, and vinyltrialkoxysilanes.
17. (New) Process according to claim 12 wherein the one or more copolymers having one or more carbonyl groups are chosen from vinyl ester-ethylene copolymers having an ethylene content of from 1 to 60% by weight,
vinyl ester-ethylene-(meth)acrylic ester copolymers having an ethylene content of from 1 to 40% by weight and a (meth)acrylic ester content of from 0.1 to 30% by weight,
vinyl acetate copolymers having from 0 to 60% by weight of one or more monomers from the group consisting of vinyl esters,
vinyl ester-(meth)acrylic ester copolymers having from 20 to 90% by weight of vinyl esters and from 0.1 to 50% by weight of one or more monomers from the group consisting of (meth)acrylic esters,
vinyl ester copolymers with esters of fumaric or maleic acid,
(meth)acrylic ester copolymers having one or more (meth)acrylic ester monomers,
styrene-(meth)acrylic ester copolymers having a styrene content of from 0.1 to 70% by weight,
styrene-butadiene copolymers having a styrene content of from 1 to 70% by weight,
vinyl chloride copolymers with vinyl esters and/or ethylene and/or (meth)acrylates.
18. (New) Process according to claim 12 wherein at least one protective colloid is at least a polyvinyl alcohol.

19. (New) Process according to claim 12 further comprising adding the thermal insulation adhesives and reinforcing mortars to a thermally insulating foam composite system.
20. (New) Process according to claim 19 wherein the composite system is a polystyrene board composite system.
21. (New) Adhesive comprising:
 - 5 to 80% by weight of fillers and/or lightweight fillers,
 - 5 to 80% by weight of mineral binders,
 - 0.5 to 50% by weight of redispersible dispersion powder having one or more copolymers stabilized with at least one protective colloid, wherein the one or more copolymers have one or more carbonyl groups and at least one of the one or more carbonyl groups are chosen from aldehyde and keto groups, and
 - 0.1 to 2% by weight of thickeners.